



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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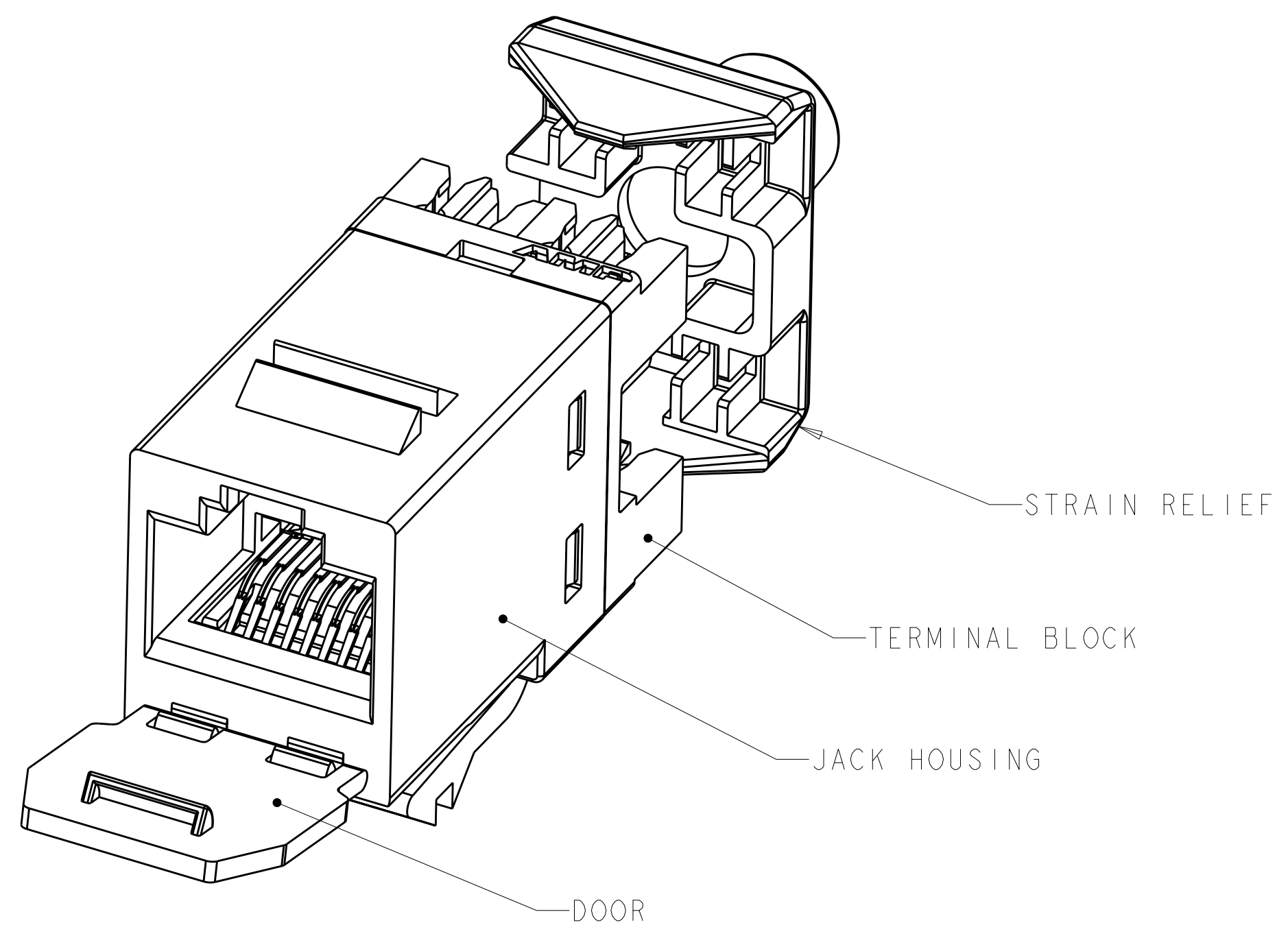
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



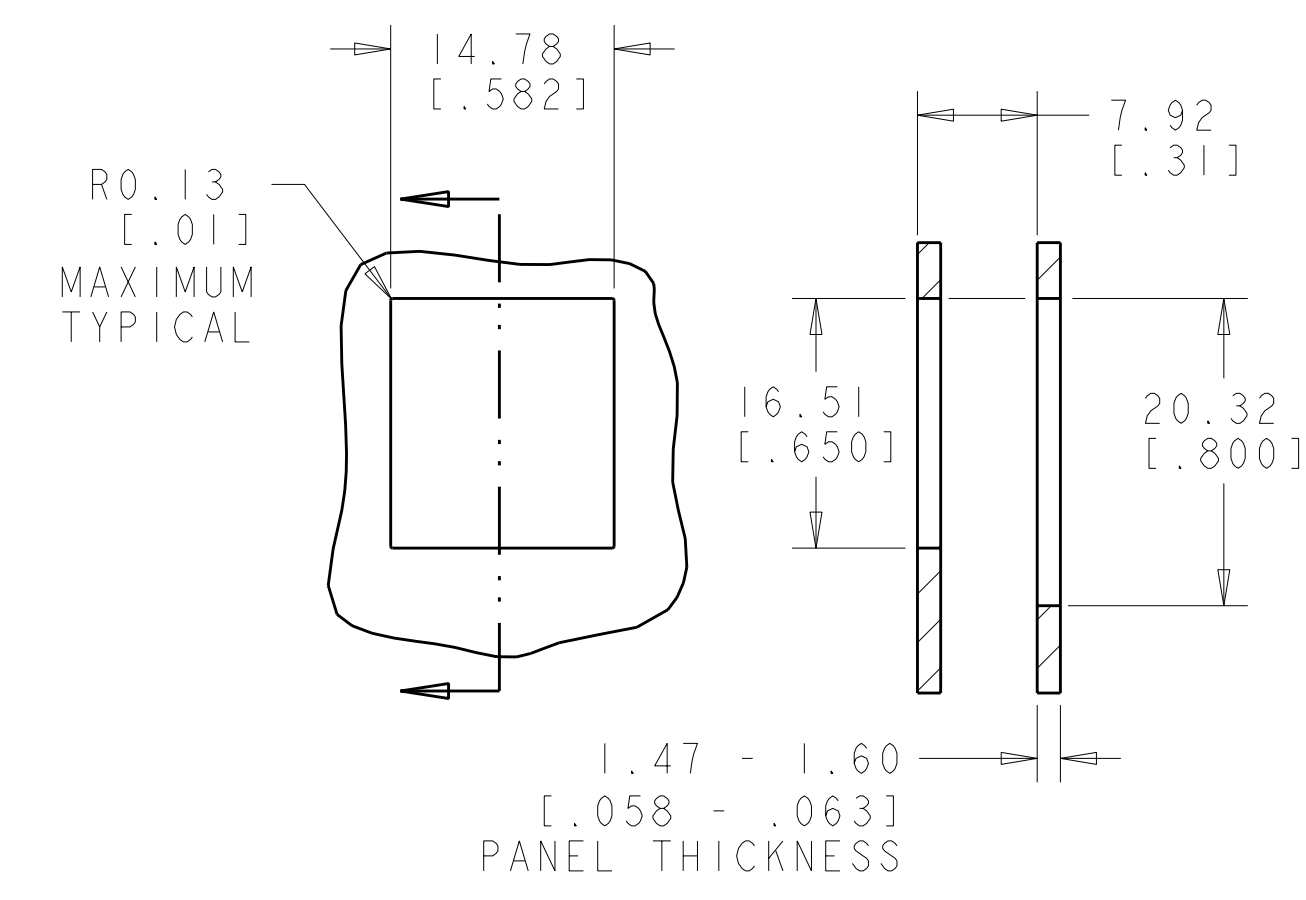
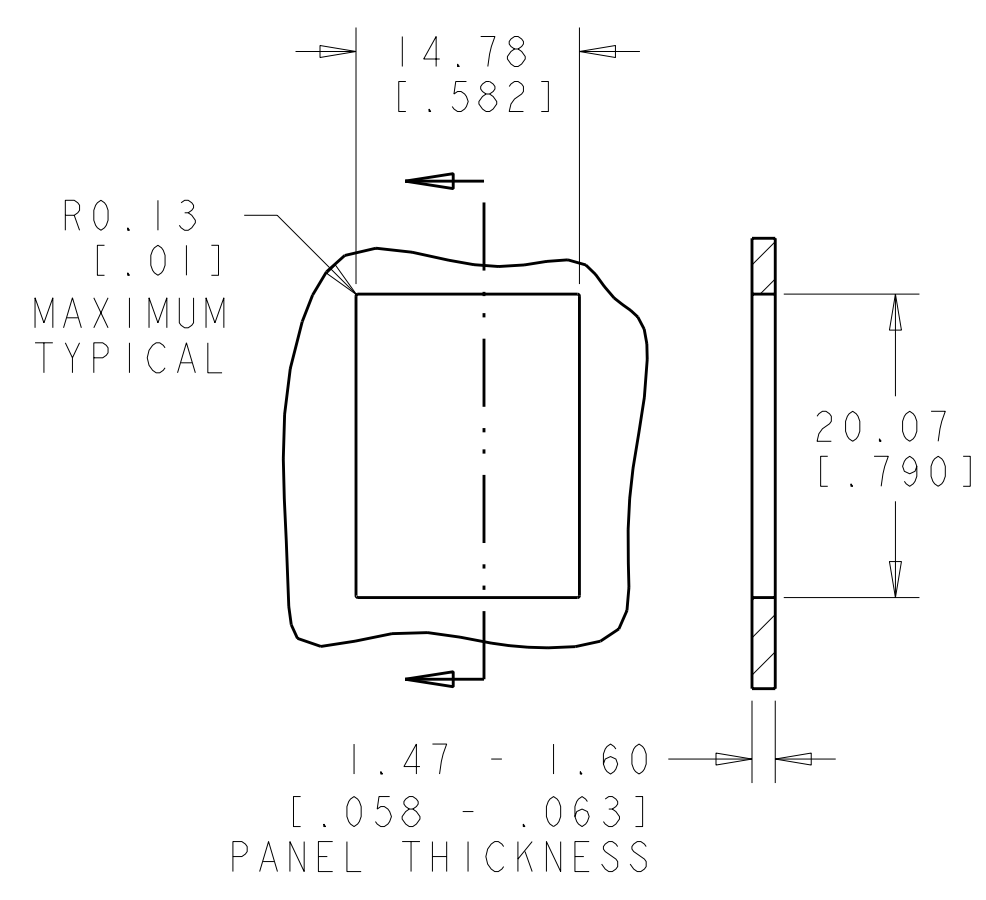
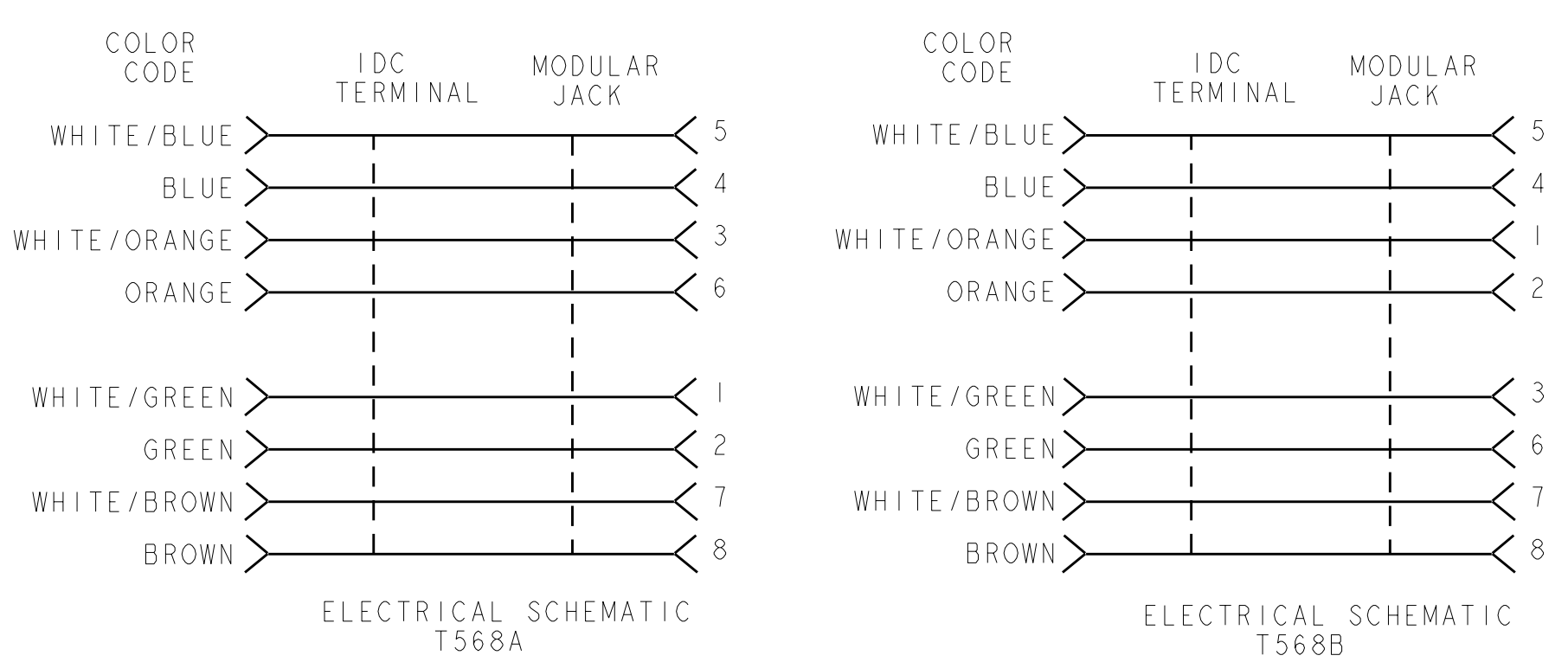
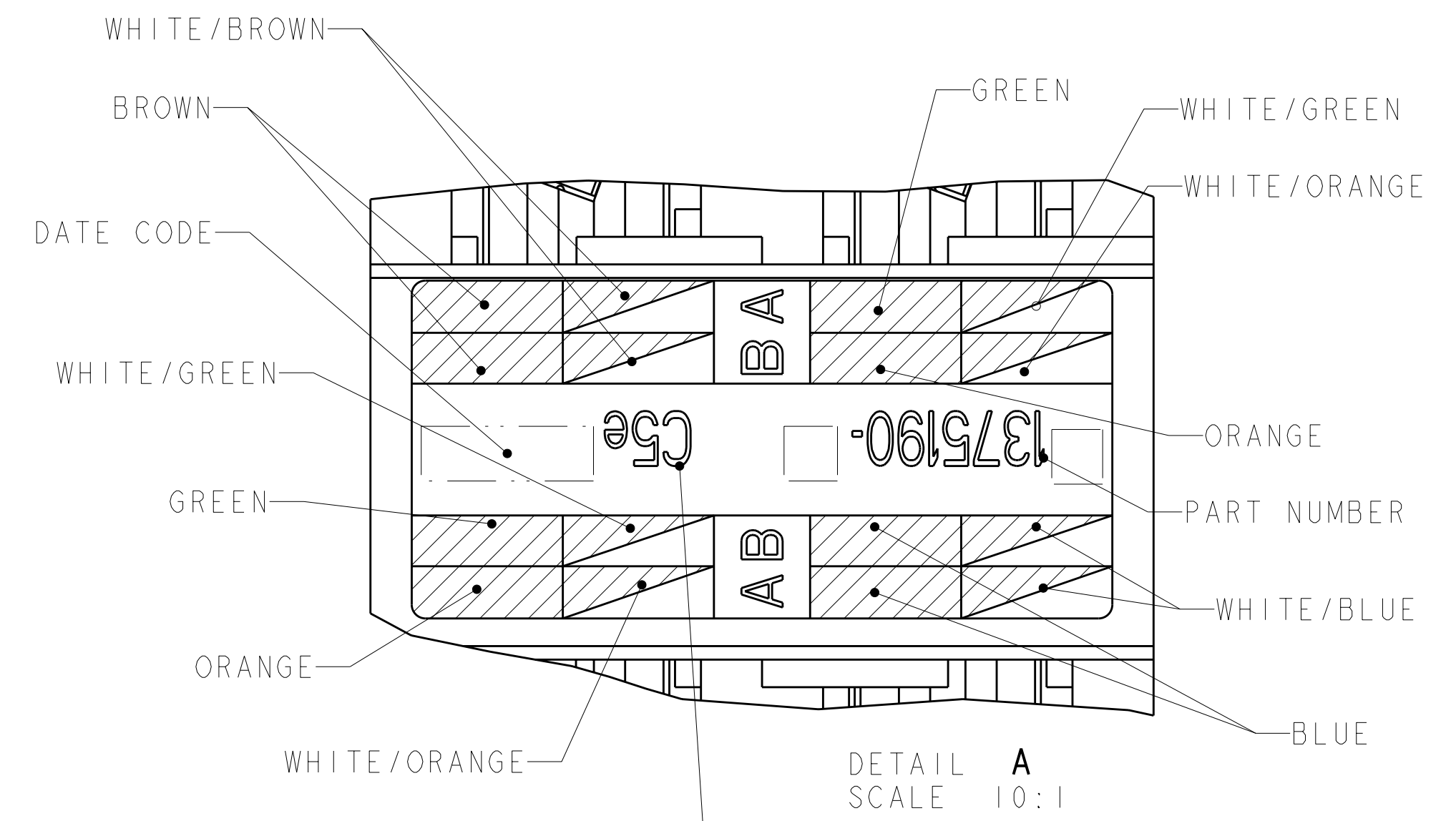
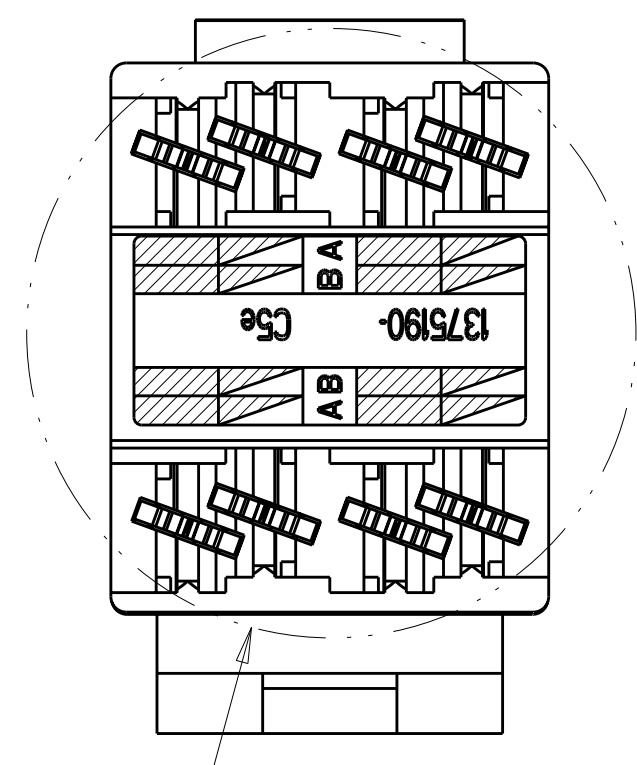
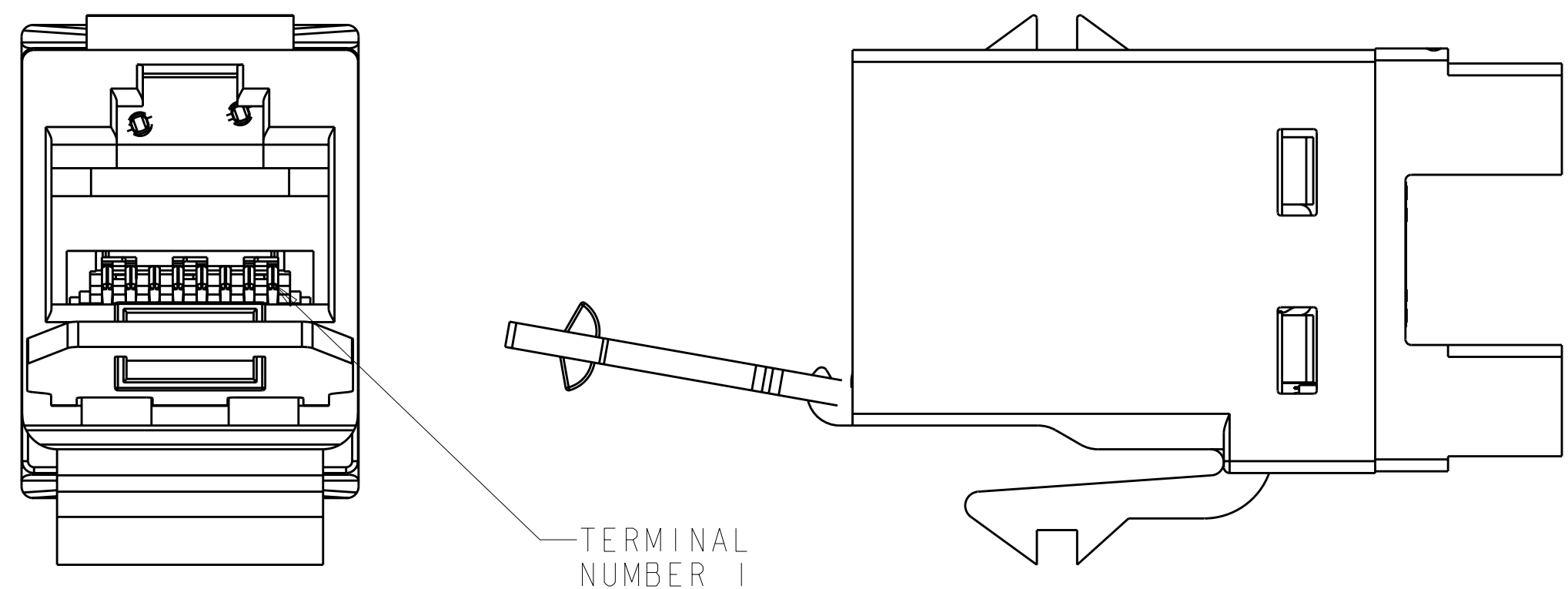
LOC	DIST	REV	DATE	BY	APPD
HM	00				

REVISIONS		DATE	BY	APPD
H	ADD 1-3, REV ECO-10-004736	08MAR2010	LH	SA
J	REV ECO-11-018963	20SEP2011	LH	SA
K	REV ECO-11-019781	07OCT2011	JB	SA



1. MATERIAL: JACK HOUSING - POLYCARBONATE, 94V-0 RATED. 110 BLOCK, STAIN RELIEF AND DOOR - POLYCARBONATE. ARRAY TRAY - PBT POLYESTER. JACK CONTACTS ARRAY - BERYLLIUM COPPER, PLATED WITH 1.27µm [.000050] MINIMUM THICK GOLD IN LOCALIZED AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN BOARD INTERFACE AREA OVER 1.27µm [.000050] MINIMUM THICK NICKEL UNDERPLATE. IDC TERMINALS - PHOSPHOROUS BRONZE, PLATED WITH 3.81µm [.00015] MINIMUM THICK MATTE TIN OVER 1.27µm [.00005] MINIMUM THICK NICKEL UNDERPLATE.
2. SL 110 JACK WILL TERMINATE 22-24 AWG SOLID AND 24-26 AWG STRANDED CONDUCTORS, 1.27[.050] MAXIMUM INSULATION DIAMETER. JACK WILL ACCEPT CONDUCTORS UP TO 1.45 [.057] BUT REQUIRE THE USE OF A STRAIN RELIEF.
3. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 SUBPART F REQUIREMENTS.
4. MOUNTING PANEL THICKNESS 1.47 - 1.60 [.058 - .063].
5. THESE TWO SUGGESTED CUTOUT OPENINGS ARE USED IN TANDEM WITH DUAL FRONT AND BACK CUTOUTS.
6. ONE MODULAR JACK ASSEMBLY AND ONE SHIELD PER POLYBAG.
7. USE OF BEND LIMITING STRAIN RELIEF IS OPTIONAL.
8. REFER TO 408-8858 FOR TERMINATION INSTRUCTIONS USING SL SERIES TOOL TERMINATION. REFER TO 408-8417 FOR TERMINATION INSTRUCTIONS USING 110 PUNCH DOWN TOOL.



PACKAGE	HOUSING COLOR	PART NUMBER
	ALPINE WHITE	1-1375190-3
	ELECTRIC IVORY	1-1375190-1
	VIOLET	1-1375190-0
	GREEN	1375190-9
	YELLOW	1375190-8
	RED	1375190-7
	BLUE	1375190-6
	ORANGE	1375190-5
	NEMA GRAY	1375190-4
	WHITE	1375190-3
	BLACK	1375190-2
	LIGHT ALMOND	1375190-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

APPROVED: T. PITTS, 05NOV01

DESIGNED: L. SMITH

DATE: 108-1990-2

PRODUCT SPEC: 108-1990-2

APPLICATION SPEC: 8

MATERIAL: 1

FINISH: 1

WEIGHT: 1

CUSTOMER DRAWING

SCALE: 4:1

SHEET: 1 OF 1

REV: K

**STE** TE Connectivity

ASSEMBLY, SL 110 JACK, DUSTCOVER, CATEGORY 5e

SIZE: CAGE CODE DRAWING NO: A100779C=1375190